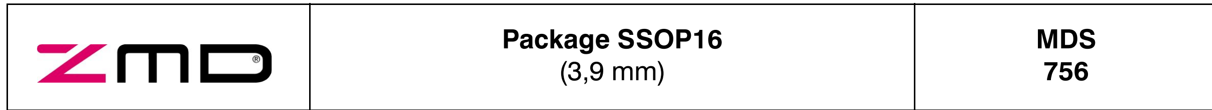


Package SSOP16
(3,9 mm)

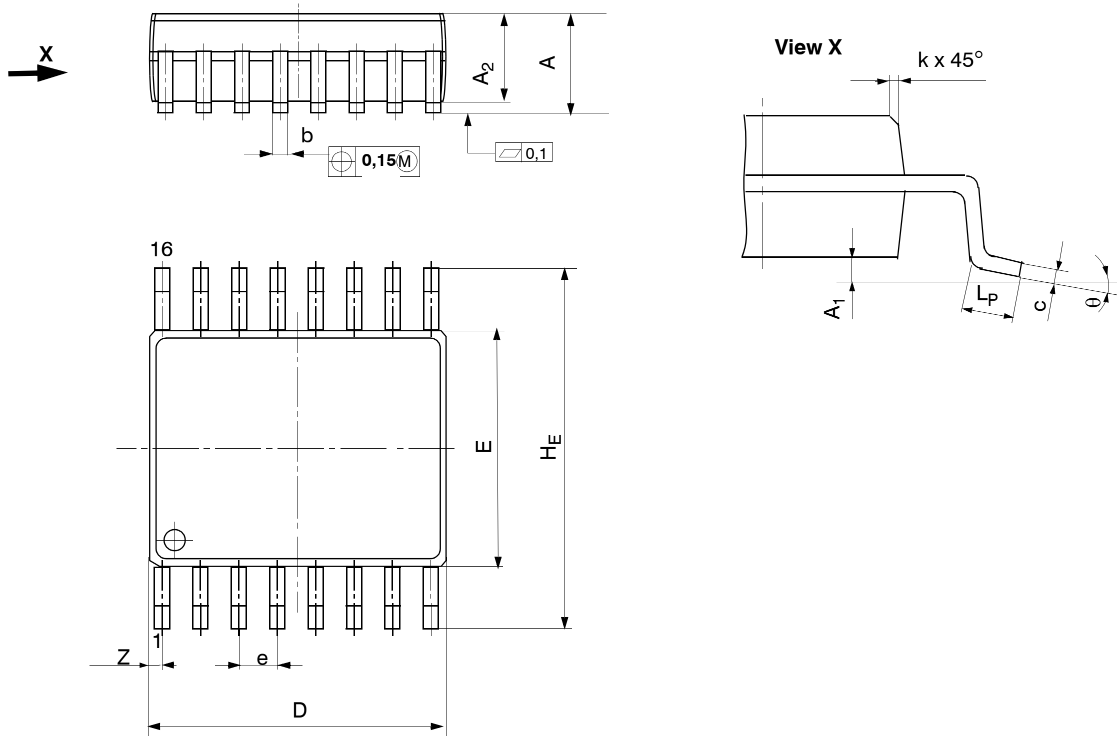
MDS 756

Supersedes
Edition 02.99

Dimensions in millimetres

Based on JEDEC JEP95: MO-137

1 Dimensions



Dimensions of Sub-Group B1	
A_{max}	1,73
b_{Pmin}	0,20
b_{Pmax}	0,30
e_{nom}	0,635
H_{Emin}	5,84
H_{Emax}	6,20
L_{Pmin}	0,41
Z_{max}	0,27

Dimensions of Sub-Group C1	
A_{min}	1,54
A_{1min}	0,10
A_{1max}	0,25
A_{2min}	1,40
A_{2max}	1,55
c_{min}	0,18
c_{max}	0,25
D_{min}*	4,80
D_{max}*	4,98
E_{min}*	3,82
E_{max}*	4,00
k_{min}	0,25
θ_{min}	0°
θ_{max}	10°

* without mold-flash

2 Weight $\leq$ 0,4 g

3 Package Body Material Low Stress Epoxy

4 Lead Material FeNi-Alloy or Cu-Alloy

5 Lead Finish solder plating

6 Lead Form Z-bends

Zentrum Mikroelektronik Dresden		
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